

SI1317DL-T1-GE3-VB Datasheet

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^c	Q _g (Typ.)			
- 20	$0.080 \text{ at V}_{GS} = -4.5 \text{ V}$	- 3.1	4.3 nC			
- 20	0.100 at V _{GS} = - 2.5 V	- 2.3	4.5110			

FEATURES

 Halogen-free According to IEC 61249-2-21 Definition



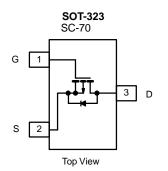
- 100 % R_a Tested
- Compliant to RoHS Directive 2002/95/EC

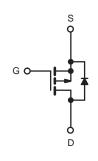




APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted) **Parameter** Symbol Limit Unit Drain-Source Voltage V_{DS} - 20 ٧ Gate-Source Voltage V_{GS} ± 12 $T_C = 25 \, ^{\circ}C$ - 3.1 T_C = 70 °C - 2.1 Continuous Drain Current (T_{.I} = 150 °C) I_D T_A = 25 °C - 1.4^{a, b} $T_A = 70 \, ^{\circ}C$ - 1.1^{a, b} Α **Pulsed Drain Current** I_{DM} - 6 $T_C = 25$ °C - 0.4 Continuous Source-Drain Diode Current I_S $T_A = 25 \, ^{\circ}C$ - 0.3 T_C = 25 °C 0.5 $T_C = 70 \, ^{\circ}C$ 0.3 Maximum Power Dissipation P_D W 0.4^{a, b} T_A = 25 °C 0.3a, b $T_A = 70 \, ^{\circ}C$ T_J, T_{stg} Operating Junction and Storage Temperature Range - 50 to 150 °С 260 Soldering Recommendations (Peak Temperature)

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Based on $T_C = 25$ °C.

服务热线:400-655-8788

1



THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	250	300	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	225	270	C/VV		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

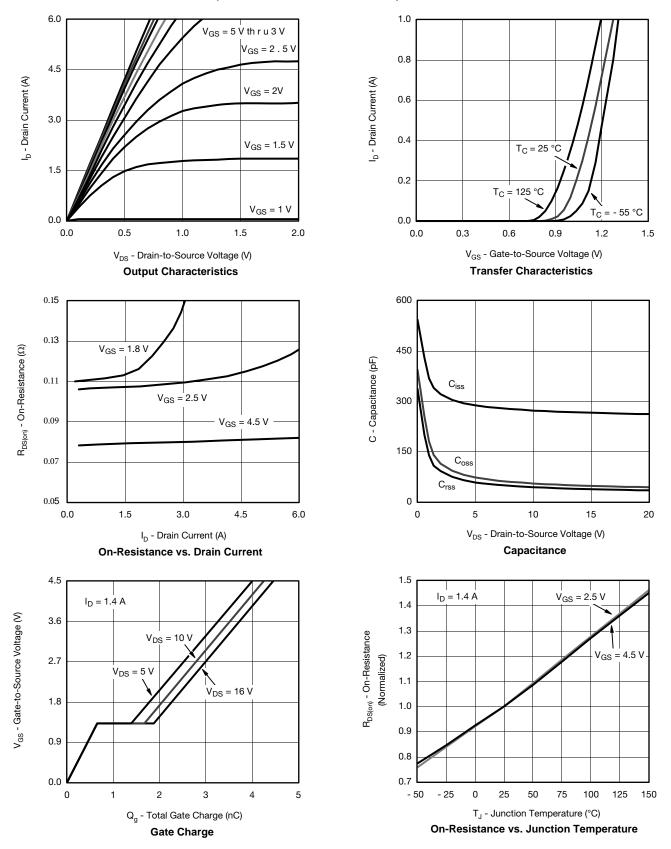
Parameter	Symbol	ymbol Test Conditions		Тур.	Max.	Unit
Static				I.	I.	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$				V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		- 14		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.4		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.45		- 1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zara Cata Valtaga Prain Current		V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μА
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C		- 10	- 10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 2			Α
		V _{GS} = - 4.5 V, I _D = - 1.4 A		0.080		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 1.2 A		0.120		
	` ′	V _{GS} = - 1.8 V, I _D = - 0.3 A		0.140		
Forward Transconductance ^a	g _{fs}	V _{DS} = - 5 V, I _D = - 1.4 A		5		S
Dynamic ^b						
Input Capacitance	C _{iss}			272		pF
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		55		
Reverse Transfer Capacitance	C _{rss}			44		
Total Cata Chausa	Q _g	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$		4.3	6.5	nC
Total Gate Charge				2.7	4.1	
Gate-Source Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -1.4 \text{ A}$		0.7		
Gate-Drain Charge	Q_{gd}			1.0		
Gate Resistance	R _q	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t _{d(on)}			12	20	
Rise Time	t _r	$V_{DD} = -10 \text{ V, R}_{L} = 9.1 \Omega$		20	30	ns
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -1.1 \text{ A, V}_{GEN} = -4.5 \text{ V, R}_{g} = 1 \Omega$		23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$		10	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1.1 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		18	27	1
Fall Time	t _f	j		7	14	1
Drain-Source Body Diode Characterist						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.4	А
Pulse Diode Forward Current ^a	I _{SM}	Ü			- 6	
Body Diode Voltage	V _{SD}	I _F = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	·		18	27	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	14	nC
Reverse Recovery Fall Time	t _a	$I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$		7		1
Reverse Recovery Rise Time	t _b	1		11		ns

Notes:

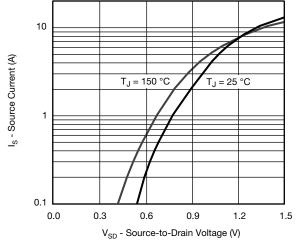
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

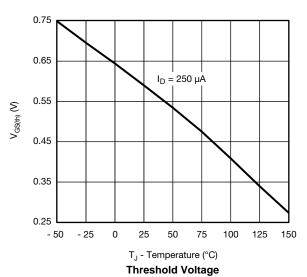


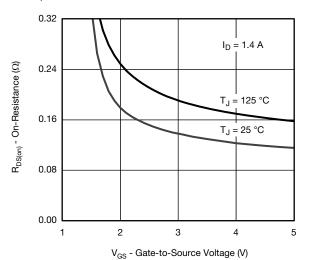




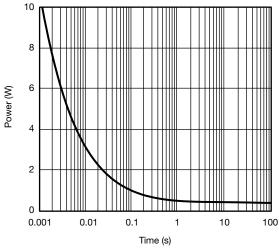


Source-Drain Diode Forward Voltage

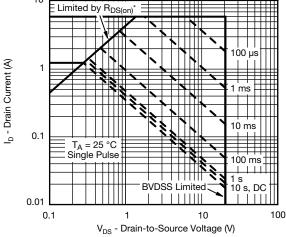




On-Resistance vs. Gate-to-Source Voltage



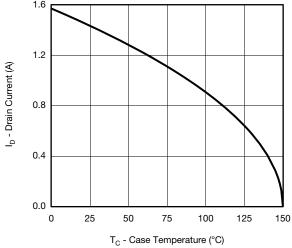
Single Pulse Power, Junction-to-Ambient



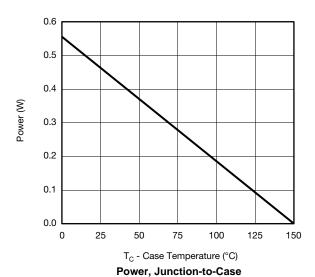
 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

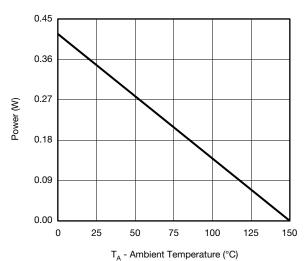
Safe Operating Area, Junction-to-Ambient







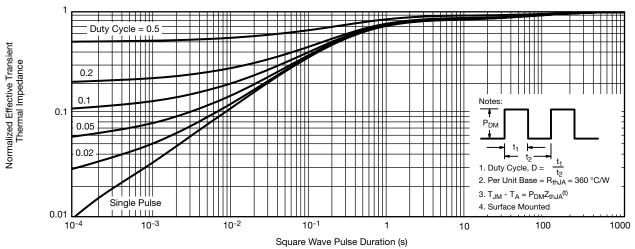




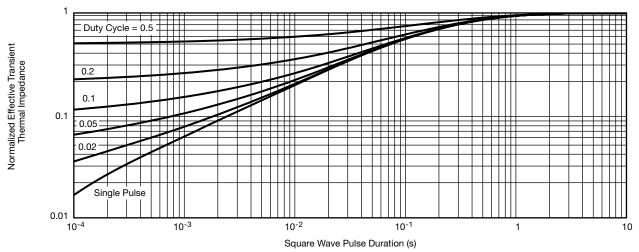
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





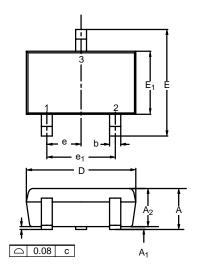
Normalized Thermal Transient Impedance, Junction-to-Ambient

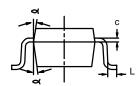


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 3-LEADS



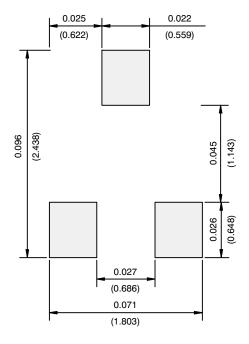


	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	_	0.043
A ₁	_	-	0.10	-	_	0.004
A ₂	0.80	-	1.00	0.031	_	0.039
b	0.25	-	0.40	0.010	_	0.016
С	0.10	-	0.25	0.004	_	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
9	7°Nom				7°Nom	
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						

8



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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